

Product Change Notice (PCN)

Subject: Add Alternate Assembly Location on Select VFQFPN Package

Publication Date: 8/4/2023

Effective Date: 11/3/2023

Revision Description:

Initial Release

Description of Change:

Renesas is adding Greatek located at Taiwan as an alternate Assembly location for select VFQFPN package. The alternate assembly location is the current qualified location for Renesas. The material sets of the current and the alternate assembly location are as shown in the below table. There will be changes in the material sets at the alternate location.

There will be no changes in the moisture sensitive level as a result of this change.

	Current	Alternate
	ASEC Taiwan	GEI Taiwan
Die attach	EN4900G	EN4900GC
Wire material	Copper wire	Copper wire
Mold compound	G700LA	G700HA

Affected Product List: Refer Appendix B.

Reason for Change:

The change is to create dual source to secure business continuity.

Impact on Fit, Form, Function, Quality & Reliability:

The change will have no impact on the form, fit, function, quality, reliability and environmental compliance of the products.

Product Identification:

Assembly lot# prefix denote Assembly Location

Prefix	Assembly Location
RC	ASEC Taiwan
GR	GEI Taiwan

Qualification Status: Completed. Refer Appendix A

Sample Availability Date: 4 weeks from sample booking date

Device Material Declaration: Available upon request

Note:

1. Acknowledgement must be received by Renesas within 30 days or Renesas will consider the change as approved.
2. If timely acknowledgement is provided by Customer, then Customer shall have 90 days from the date of receipt of this PCN to make any objections to this PCN. If Customer fails to make objections to this PCN within 90 days of the receipt of the PCN then Renesas will consider the PCN changes as approved.
3. If customer cannot accept the PCN then customer must provide Renesas with a last time buy demand and purchase order.

For additional information regarding this notice, please contact idt-pcn@lm.renesas.com

Appendix A - Qualification Results
Affected Package: VFQFPN-24

Qual Vehicle: VFQFPN-24

Assembly Material: As shown in page 1

Qual Plan & Results: Tests are in accordance with JEDEC47 recommended tests.

Test Descriptions	Test Method	Test Results (Rej/SS)		
		Lot 1	Lot 2	Lot 3
* Temperature Cycling (-55 °C to 125 °C, 700 cycles)	JESD22-A104	0/25	0/25	0/25
* HAST - unbiased (130 °C/85% RH, 96 Hrs)	JESD22-A118	0/25	0/25	0/25
High Temperature Storage Bake (150 °C, 1000 Hrs)	JESD22-A103	0/25	0/25	0/25
Ball Shear Test	JESD22-B116	0/5	0/5	0/25
Bond Pull Test	MIL-STD-883 (Method 2011)	0/5	0/5	0/5
Physical Dimensions	JESD22-B100	0/30	0/30	0/30
Solderability Test	MIL-STD-883 (Method 2003)	0/5	0/5	0/5
Moisture Sensitivity Level, MSL	J-STD-20 / MSL 1, 260 °C	0/25	0/25	-

*Tests were subjected to Preconditioning per JESD22-A113 prior to stress test

Appendix B – Affected Product List

F1192BNLGK	F1421NLGK	F1192NLGK8	F1192NLGI
F1792NLGI	F1420NLGK8	F1192NLGK	F1192BNLGK8
F1421NLGK8	F1420NLGK	F1192NLGI8	F1792NLGI8